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| Title | | U.C. BERKELEY | | |
| Size | Number | Rev | | |
| B | EPIC USB | 1 | | |
| Date | Wed Oct 10 2007 | Drawn by G.MYERS | | |
| Filename | EPIC_USB.PCB | Sheet | of | 5 |

NOTES:

- UNLESS OTHERWISE NOTED, ALL DIMENSIONS ARE IN INCHES.
- MATERIAL: FINISHED BOARD THICKNESS = SEE ORDER FORM.
EPOXYGLASS, NEMA TYPE FR-4, EACH LAYER COPPER THICKNESS TO BE EQUIVALENT TO 1 OZ./SQ.FT.
LAYER STACK: 1) TOP 2) GND 3) ML1 4) BOT
LAYER SPACING = SEE ORDER FORM.
- PLATE ALL HOLES THROUGH 0.0010 INCH MINIMUM COPPER PLUS 0.0003 INCH MINIMUM SOLDER SIDEWALL THICKNESS, UNLESS NOTED OTHERWISE. ALL HOLE DIAMETERS ARE FINISHED SIZES. TOLERANCE IS +/- 0.003 INCH.
- THERE ARE 2 SOLDER MASKS, TOP (.TSM) & BOTTOM (.BSM).
SOLDER MASK BOTH SIDES (HYSOL SR1020 OR EQUIVALENT) OVER BARE COPPER (SMOBC), WITH GOLD ON THE EXPOSED PADS.
SOLDER MASK COLOR = SEE ORDER FORM.
- COMPONENT SCREEN OVER SOLDER MASK, TOP (.TSS) AND BOTTOM (.BSS).
SILKSCREEN COLOR = SEE ORDER FORM.
- USE 0.0625 ROUTER FOR LARGE ROUTED SLOTS, DO NOT PLATE.
OK TO ROUTE OFF 1/2 OF THE PERIMETER PADS.
USE 0.020 ROUTER FOR SMALL SLOTS, DO NOT PLATE.

